

### **Peak EMI Reducing Solution**

#### **Features**

- Generates an EMI optimized clocking signal at output.
- Input frequency 25 MHz.
- Frequency outputs:
  - o 60 MHz (unmodulated)
  - o 2 x 48 MHz (unmodulated)
  - o 66.6 MHz (modulated) -1.7% down spread
- Modulation rate: 30 KHz.
- Supply voltage range: 3.3V ± 0.3V.
- Available in 8-pin SOIC Package.
- Commercial and Industrial Temperature range.

#### **Product Description**

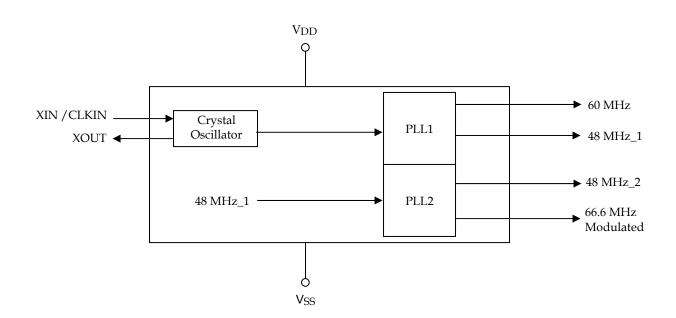
The ASM3P2111A is a versatile spread spectrum frequency modulator. The ASM3P2111A reduces electromagnetic interference (EMI) at the clock source.

The ASM3P2111A allows significant system cost savings by reducing the number of circuit board layers and shielding that are required to pass EMI regulations. The ASM3P2111A modulates the output of PLL in order to spread the bandwidth of a synthesized clock, thereby decreasing the peak amplitudes of its harmonics. This results in significantly lower system EMI compared to the typical narrow band signal produced by oscillators and most clock generators. Lowering EMI by increasing a signal's bandwidth is called spread spectrum clock generation.

#### **Applications**

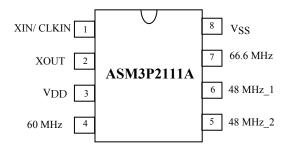
ASM3P2111A is targeted towards EMI management for high speed digital applications such as PC peripheral devices, consumer electronics and embedded controller systems.

#### **Block Diagram**





# **Pin Configuration**



# **Pin Description**

Pin Name	Type	Description	
XIN / CLKIN	1	Connection to crystal	
XOUT	0	Connection to crystal	
$V_{DD}$	Р	Power supply for the analog and digital blocks(+3.3V)	
60 MHz	0	Clock output-1 60 MHz unmodulated	
48 MHz_2	0	Clock output-2 48 MHz_2 unmodulated	
48 MHz_1	0	Clock output-3 48 MHz_1 unmodulated	
66.6 MHz	0	Clock output-4 66.6 MHz modulated	
$V_{SS}$	Р	Ground to entire chip	



# **Absolute Maximum Ratings**

Parameter	Rating	Unit	
Voltage on any pin with respect to Ground	-0.5 to +7.0	V	
Storage temperature	-65 to +125	°C	
Operating temperature	0 to 70	°C	
Max. Soldering Temperature (10 sec)	260	°C	
Junction Temperature	150	°C	
Static Discharge Voltage (As per JEDEC STD 22- A114-B)	2	KV	
	Voltage on any pin with respect to Ground Storage temperature Operating temperature Max. Soldering Temperature (10 sec) Junction Temperature Static Discharge Voltage	Voltage on any pin with respect to Ground  -0.5 to +7.0  Storage temperature  -65 to +125  Operating temperature  0 to 70  Max. Soldering Temperature (10 sec)  Junction Temperature  Static Discharge Voltage	

Note: These are stress ratings only and are not implied for functional use. Exposure to absolute maximum ratings for prolonged periods of time may affect device reliability.

# **Operating Conditions**

Parameter	Symbol	Condition / Description	Min	Тур	Max	Unit
Supply Voltage	$V_{DD}$	$3.3V \pm 0.3V$	3	3.3	3.6	V
Crystal Resonator Frequency	F <sub>XIN</sub>		25	-	ı	MHz
Output Driver Load Capacitance	$C_L$		-	-	15	pF



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### **DC Electrical Characteristics**

Parameter	Symbol	Conditions / Description	Min	Тур	Max	Unit	
Overall							
Supply Current, Dynamic	I <sub>DD</sub>	V <sub>DD</sub> =3.3V, F <sub>CLK</sub> =25MHz, C <sub>L</sub> =15pF	41	48	62	mA	
Supply Current, Static	I <sub>DDL</sub>	V <sub>DD</sub> = 3.3V, Clock Input = 0	20	25	35	mA	
All input pins							
High-Level Input Voltage	V <sub>IH</sub>	V <sub>DD</sub> =3.3V	2.0	-	V <sub>DD</sub> +0.3	V	
Low-Level Input Voltage	V <sub>IL</sub>	V <sub>DD</sub> =3.3V	V <sub>SS</sub> -0.3	-	0.8	V	
High-Level Input Current	I <sub>IH</sub>		-1	-	1	μΑ	
Low-Level Input Current (pull-up)	I <sub>IL</sub>		-20	-36	-80	μΑ	
High-Level Output Source Current	I <sub>xOH</sub>	V <sub>DD</sub> =V (XIN) = 3.3V, V <sub>O</sub> =0.4V	-	3	-	mA	
Low-Level Output Sink Current	I <sub>xOL</sub>	V <sub>DD</sub> =3.3V, V (XIN)=V <sub>O</sub> =2.5V	-	3	-	mA	
Clock Outputs							
High-Level Output Source Current	Іон	V <sub>O</sub> =2.5V	-	-20	-	mA	
Low-Level Output Sink Current	l <sub>OL</sub>	V <sub>O</sub> =0.4V	-	23	-	mA	
Output Impedance	Z <sub>OH</sub>	V <sub>O</sub> =0.5V <sub>DD</sub> ; output driving high	-	29	-	Ω	
Output impedance	Z <sub>OL</sub>	Vo=0.5V <sub>DD</sub> ; output driving low	-	27	-		

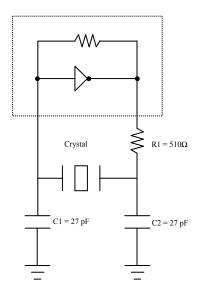
#### **AC Electrical Characteristics**

Parameter	Symbol	Conditions/ Description	Min	Тур	Max	Unit
Rise Time	t <sub>r</sub>	$V_0 = 0.8V \text{ to } 2.0V;$ $C_L = 15pF$	300	800	900	pS
Fall Time	t <sub>f</sub>	V <sub>O</sub> = 2.0V to 0.8V; C <sub>L</sub> = 15pF	360	800	900	pS
Clock Duty Cycle  Ratio of pulse width (as measured from rising edge to next falling edge at 2.5V) to one clock period  A 55					%	



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# **Crystal Oscillator Circuit**



# **Crystal Specifications**

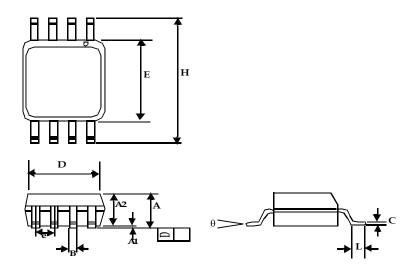
Fundamental AT cut parallel resonant crystal				
Nominal frequency	25 MHz			
Frequency tolerance	± 50 ppm or better at 25°C			
Operating temperature range	-25°C to +85°C			
Storage temperature	-40°C to +85°C			
Load capacitance	18pF			
Shunt capacitance	7pF maximum			
ESR	25 Ω			



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# **Package Information**

# 8-Pin SOIC Package



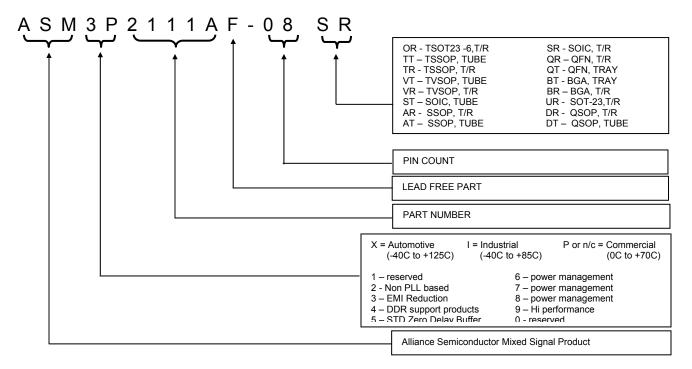
	Dimensions				
Symbol	Inches		Millimeters		
	Min	Max	Min	Max	
A1	0.004	0.010	0.10	0.25	
Α	0.053	0.069	1.35	1.75	
A2	0.049	0.059	1.25	1.50	
В	0.012	0.020	0.31	0.51	
С	0.007	0.010	0.18	0.25	
D	0.193 BSC		4.90 BSC		
Е	0.154 BSC		3.91 BSC		
е	0.050 BSC		1.27 BSC		
Н	0.236 BSC		6.00	BSC	
L	0.016	0.050	0.41	1.27	
θ	0°	8°	0°	8°	



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Ordering Codes

Part number	MARKING	Package Configuration	Temperature Range	
ASM3P2111AF-08ST	3P2111AF	8-pin SOIC TUBE, Pb Free	Commercial	
ASM3P2111AF-08SR	3P2111AF	8-pin SOIC TAPE & REEL, Pb Free	Commercial	
ASM3I2111AF-08ST	3I2111AF	8-pin SOIC TUBE, Pb Free	Industrial	
ASM3I2111AF-08SR	3I2111AF	8-pin SOIC TAPE & REEL, Pb Free	Industrial	

#### **Ordering Information**



Licensed under US patent #5,488,627, #6,646,463 and #5,631,920.



Alliance Semiconductor Corporation 2575, Augustine Drive, Santa Clara, CA 95054 Tel# 408-855-4900 Fax: 408-855-4999 www.alsc.com Copyright © Alliance Semiconductor All Rights Reserved Part Number: ASM3P2111A Document Version: v1.3

Note: This product utilizes US Patent #6,646,463 Impedance Emulator Patent issued to Alliance Semiconductor, dated 11-11-2003

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